

Abstract

Methods and structures for die packages are described. The die package includes an integrated circuit die connected to and elevated above a substrate. In an embodiment, wire bonds connects pads on the die to pads on the substrate. The
5 substrate pads are closely adjacent the die due to the die support being positioned inwardly of the peripheral surface of the die. In an embodiment, the die support includes a paste that flows outwardly when connecting the die to the substrate. The outward paste flow extends from beneath the die support but does not extend outwardly of the die so as to not interfere or contact the substrate pads.

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